

Vishay Siliconix

P-Channel 20-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY						
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^a	Qg			
	0.094 at $V_{GS} = -4.5 V$	- 4.5				
- 20	0.131 at V _{GS} = - 2.5 V	- 4.5	4.9 nC			
	0.185 at V _{GS} = -1.8 V	- 4.5				

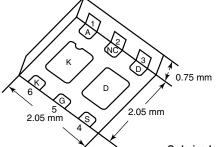
SCHOTT	SCHOTTKY PRODUCT SUMMARY					
V _{KA} (V)	V _f (V) Diode Forward Voltage	I _F (A) ^a				
20	0.46 at 0.5 A	1				

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- LITTLE FOOT[®] Plus Schottky Power MOSFET
- New Thermally Enhanced PowerPAK[®] SC-70 Package
 - Small Footprint Area
 - Low On-Resistance
 - Thin 0.75 mm Profile
- Compliant to RoHS Directive 2002/95/EC

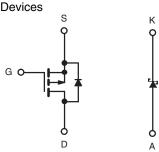
APPLICATIONS

- Cellular Charger Switch
- Buck Converter for Portable Devices
- Load Switch for Portable Devices



PowerPAK SC-70-6 Dual

Marking Code Part # code H B X • X X X Lot Traceability and Date code



Ordering Information: SiA813DJ-T1-GE3 (Lead (Pb)-free and Halogen-free) P-Channel P-Ch

P-Channe	IMOSFET

Parameter		Symbol	Limit	Unit
Drain-Source Voltage (MOSFET)		V _{DS}	- 20	
Reverse Voltage (Schottky)		V _{KA}	20	V
Gate-Source Voltage (MOSFET)		V _{GS}	± 8	
	T _C = 25 °C		- 4.5 ^a	
Continuous Drain Current (T _J = 150 °C) (MOSFET)	T _C = 70 °C		- 4.5 ^a	_
	T _A = 25 °C	I _D	- 3.6 ^{b, c}	
	T _A = 70 °C		- 2.9 ^{b, c}	
Pulsed Drain Current (MOSFET)		I _{DM}	- 8	A
Continuous Source-Drain Diode Current	T _C = 25 °C	la la	- 4.5 ^a	
(MOSFET Diode Conduction)	T _A = 25 °C	I _S	- 1.6 ^{b, c}	
Average Forward Current (Schottky)		۱ _F	1 ^b	
Pulsed Forward Current (Schottky)		I _{FM}	2	
	T _C = 25 °C		6.5	
Maximum Power Dissipation (MOSFET)	T _C = 70 °C		5	
	T _A = 25 °C		1.9 ^{b, c}	
	T _A = 70 °C	P _D	1.2 ^{b, c}	w
	T _C = 25 °C	' D	7.3	
Maximum Power Dissipation (Schottky)	T _C = 70 °C		4.7	
Maximum Fower Dissipation (Schottky)	T _A = 25 °C		2.3 ^{b, c}	
	T _A = 70 °C		1.5 ^{b, c}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	
Soldering Recommendations (Peak Temperature) ^{d, e}			260	



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THERMAL	RESISTANCE	RATINGS
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Parameter	Symbol	Typical	Maximum	Unit						
Maximum Junction-to-Ambient (MOSFET) ^{b, f}	t ≤ 5 s	R _{thJA}	52	65						
Maximum Junction-to-Case (Drain) (MOSFET) Steady S		R _{thJC}	12.5	16	°C/W					
Maximum Junction-to-Ambient (Schottky) ^{b, g}	t ≤ 5 s	R _{thJA}	40	55	0/10					
Maximum Junction-to-Case (Drain) (Schottky)	Steady State	R _{thJC}	13	17						

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. See solder profile (<u>www.vishay.com/ppg?73257</u>). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under steady state conditions for MOSFET is 110 °C/W. g. Maximum under steady state conditions for Schottky is 85 °C.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	·					
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 16.2		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	η _D = - 250 μΑ		2.1		mv/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 0.4		- 1	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA
Zero Gate Voltage Drain Current	=	$V_{DS} = -20 V, V_{GS} = 0 V$			- 1	
Zero Gale voltage Dialit Current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			± 100	- μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5$ V, $V_{GS} = -4.5$ V	- 8			A
		V _{GS} = - 4.5 V, I _D = - 2.8 A		0.078	0.094	Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -2.3 \text{ A}$		0.109	0.131	
		V _{GS} = - 1.8 V, I _D = - 0.54 A		0.153	0.185	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 2.8 A		7		S
Dynamic ^b	•					•
Input Capacitance	C _{iss}			355		
Output Capacitance	C _{oss}	$V_{DS} = -10 V$, $V_{GS} = 0 V$, f = 1 MHz		75		pF
Reverse Transfer Capacitance	C _{rss}			50		
Total Gate Charge		$V_{DS} = -10 \text{ V}, \text{ V}_{GS} = -8 \text{ V}, \text{ I}_{D} = -4.5 \text{ A}$		8.5	13	
Iotal Gate Charge	Qg			4.9	7.4	
Gate-Source Charge	Q _{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -4.5 \text{ A}$		0.75		nC
Gate-Drain Charge	Q _{gd}			1.2		
Gate Resistance	Rg	f = 1 MHz		8		Ω
Turn-On Delay Time	t _{d(on)}			10	15	
Rise Time	t _r	V_{DD} = - 10 V, R_L = 2.2 Ω		35	55	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 4.5 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		40	60	
Fall Time	t _f		50	75	1	
Turn-On Delay Time	t _{d(on)}			5	10	ns
Rise Time	t _r	V_{DD} = - 10 V, R_L = 2.2 Ω		10	15	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -4.5 \text{ A}, \text{ V}_{\text{GEN}} = -8 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		20	30	
Fall Time	t _f	, j		10	15	1



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SPECIFICATIONS $T_J = 25 \text{ °C}$, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 4.5	Α		
Pulse Diode Forward Current	I _{SM}				- 8	A		
Body Diode Voltage	V _{SD}	I _S = - 4.5 A, V _{GS} = 0 V		- 0.85	- 1.2	V		
Body Diode Reverse Recovery Time	t _{rr}			30	60	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	- Ι _F = - 4.5 A, dl/dt = 100 A/μs, Τ _{.1} = 25 °C		13	26	nC		
Reverse Recovery Fall Time	t _a	$F = -4.5 \text{ A}, \text{ u/u} = 100 \text{ A/} \mu\text{s}, \text{ f} \text{ J} = 25 \text{ C}$		10		ns		
Reverse Recovery Rise Time	t _b			15		- 115		

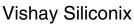
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

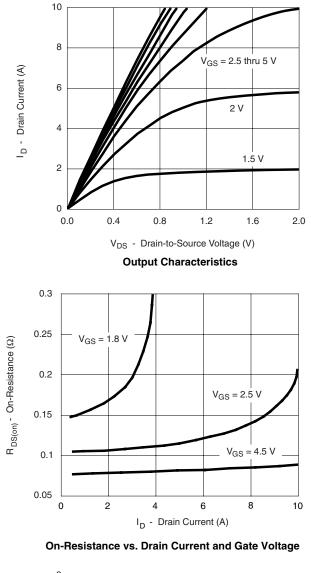
SCHOTTKY SPECIFICATIONS $T_J = 25 \text{ °C}$, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
		I _F = 0.5 A		0.381	0.46		
Forward Voltage Drop	V _F	I _F = 1 A		0.468	0.560	V	
		I _F = 1 A, T _J = 125 °C		0.44	0.46		
		V _r = 5 V		0.0081	0.041		
		V _r = 5 V, T _J = 85 °C		0.4	4		
		V _r = 5 V, T _J = 125 °C		2.8	28	1	
		V _r = 10 V			0.043		
Maximum Reverse Leakage Current	I _{rm}	V _r = 10 V, T _J = 85 °C		0.5	5	mA	
		V _r = 10 V, T _J = 125 °C		3	30		
		V _r = 20 V		0.0093	0.047		
		V _r = 20 V, T _J = 85 °C		0.5	5		
		V _r = 20 V, T _J = 125 °C		3.2	32	1	
Junction Capacitance	CT	V _r = 10 V		30		pF	

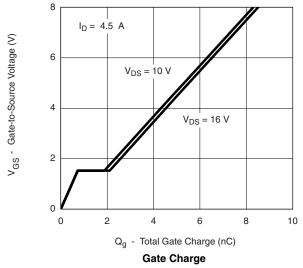
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

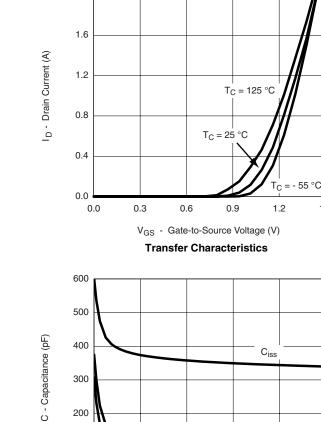


MOSFET TYPICAL CHARACTERISTICS $T_A = 25 \degree$ C, unless otherwise noted

2.0

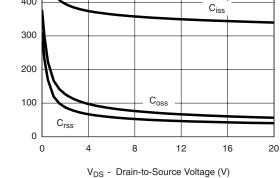




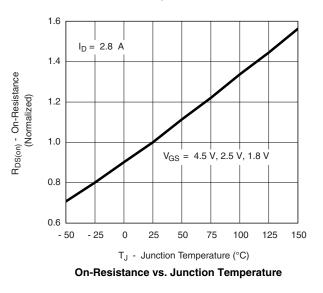


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1.5



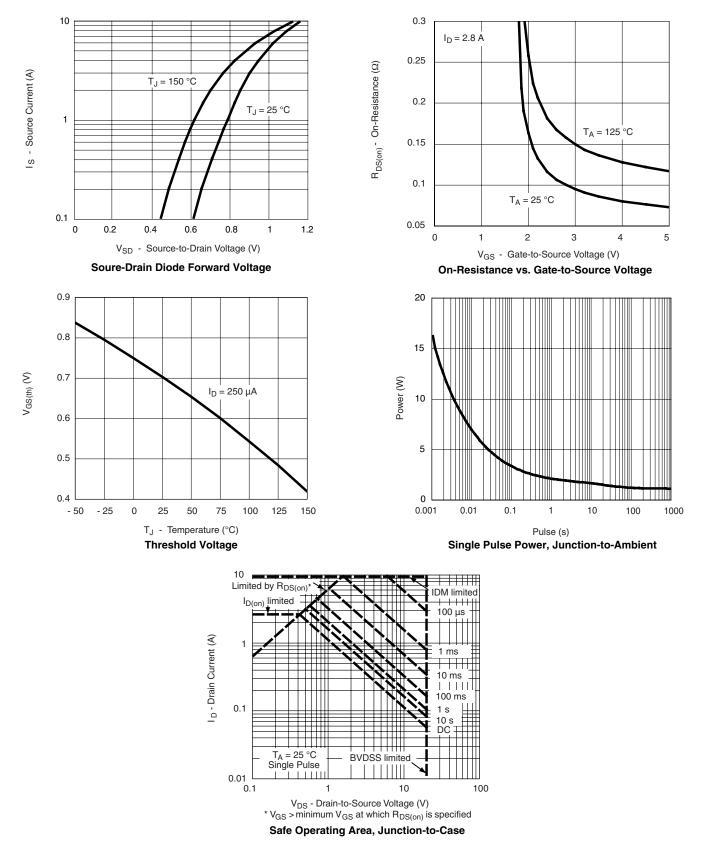
Capacitance





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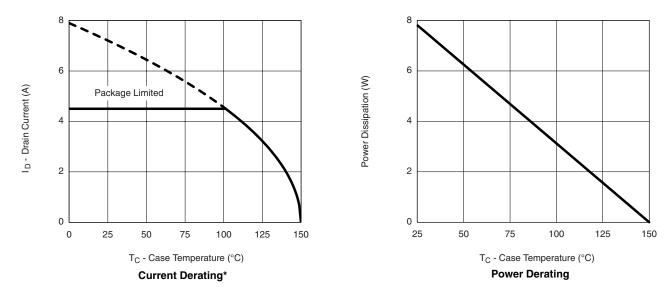
MOSFET TYPICAL CHARACTERISTICS T_A = 25 °C, unless otherwise noted



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MOSFET TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

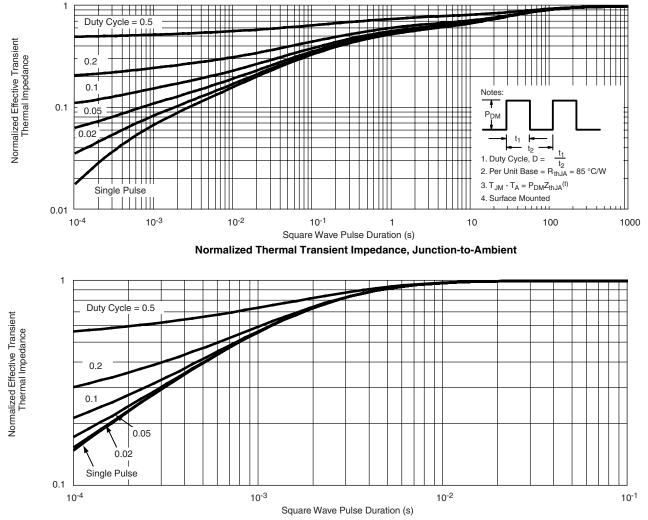


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



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MOSFET TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

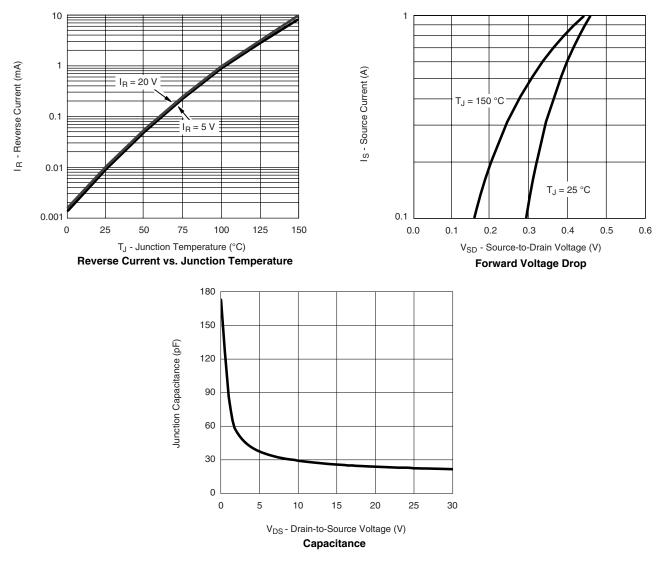


Normalized Thermal Transient Impedance, Junction-to-Case

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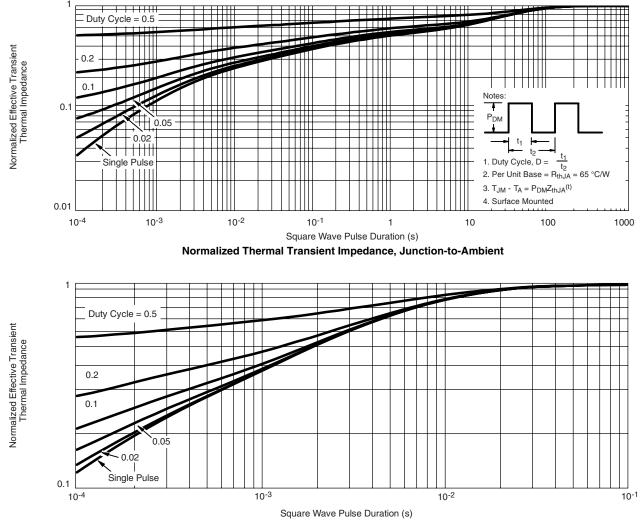
SCHOTTKY TYPICAL CHARACTERISTICS $T_A = 25 \text{ °C}$, unless otherwise noted





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SCHOTTKY TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?70450.



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